










PCN Number:	20190318002.1		PCN Date:	Mar 20, 2019																						
Title:	Qualification of RFAB as an additional Wafer Fab Site option for select devices in HPA07 Technology																									
Customer Contact:	PCN Manager		Dept:	Quality Services																						
Proposed 1st Ship Date:	Jun 20, 2019		Estimated Sample Availability:	Date provided at sample request.																						
Change Type:																										
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																					
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																					
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																					
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																					
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																					
		<input type="checkbox"/>	Part number change																							
PCN Details																										
Description of Change:																										
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in "Product Affected" section.																										
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th colspan="3" style="text-align: center;">Current Sites</th> <th colspan="3" style="text-align: center;">Additional Sites</th> </tr> <tr> <th style="text-align: center;">Current Fab Site</th> <th style="text-align: center;">Process</th> <th style="text-align: center;">Wafer Diameter</th> <th style="text-align: center;">Additional Fab Site</th> <th style="text-align: center;">Process</th> <th style="text-align: center;">Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">DP1DM5</td> <td style="text-align: center;">HPA07</td> <td style="text-align: center;">200mm</td> <td rowspan="2" style="text-align: center;">RFAB</td> <td rowspan="2" style="text-align: center;">HPA07</td> <td rowspan="2" style="text-align: center;">300mm</td> </tr> <tr> <td style="text-align: center;">AIZU</td> <td style="text-align: center;">HPA07</td> <td style="text-align: center;">200mm</td> </tr> </tbody> </table>						Current Sites			Additional Sites			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	DP1DM5	HPA07	200mm	RFAB	HPA07	300mm	AIZU	HPA07	200mm
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DP1DM5	HPA07	200mm	RFAB	HPA07	300mm																					
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Qual details are provided in the Qual Data Section.																										
Reason for Change:																										
Continuity of Supply																										
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																										
None																										
Changes to product identification resulting from this PCN:																										
Current																										
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City																							
DP1DM5	DM5	USA	Dallas																							
AIZU	CU2	JPN	Aizuwakamatsu-shi																							
New Fab Site																										
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City																							
RFAB	RFB	USA	Richardson																							
Sample product shipping label (not actual product label)																										
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MSL '2 / 260C / 1 YEAR	SEAL DT																									
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Product Affected Group:																										
ADS8028IRTJR		ADS8028IRTJT																								

Qualification Report

Approve Date 18-February-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ADS8028IRTJR	QBS Process Reference: CD3232A1YFFR	QBS Package Reference: SH6966ACC0RGCRG4
AC	Autoclave, 121C/2 atm	96 Hours	-	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/3000/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0
HBM	ESD - HBM	2500 V	1/3/0	3/9/0	-
CDM	ESD - CDM	1000 V	1/3/0	3/9/0	-
HTOL	Life Test, 150C	300 Hours	3/231/0	-	-
HTOL	Life Test, 140C	480 Hours	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/231/0	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	3/18/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	3/231/0	-

- QBS: Qual By Similarity

- Qual Device ADS8028IRTJR is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com